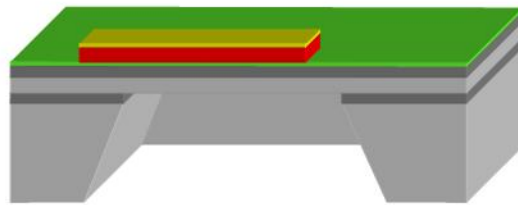




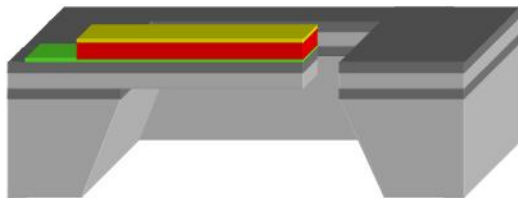
Starting point:  
Oxidised silicon-on-insulator wafer (SOI).



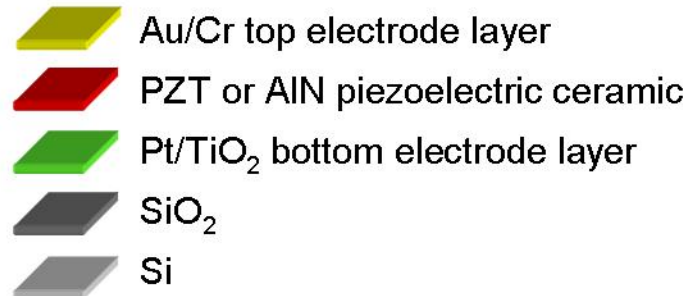
Backside opening by wet etch,  
Pt bottom electrode by sputtering,  
Piezoelectric layer by CSD, sputtering or PLD,  
Au/Cr top electrode by vapour deposition and  
lift off patterning.



Patterning of piezoelectric layer by wet etch,  
Back side cavity removal by wet etch.



Release by reactive ion etch.



*Piezoelectric MEMS devices are produced through a series of deposition and etching steps.*